TE Internal #: 2375157-1 LGA 7529, 7529 Position, Surface Mount - Solder Ball, .81389 x . 9398 mm Grid, Board Mount, LGA Sockets

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Connectors > Socket Connectors > IC Sockets > LGA Sockets











IC Socket Type: LGA 7529

Contact Mating Area Plating Material Thickness: [30 µin]

Number of Positions: 7529

Termination Method to PCB: Surface Mount - Solder Ball

Grid Spacing: .81389 x .9398 mm

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Board-to-Component

Configuration Features

Number of Positions	7529
Grid Spacing	.81389 x .9398 mm

Contact Features

Contact Mating Area Plating Material	Gold (Au)
Contact Base Material	Copper Alloy
IC Socket Type	LGA 7529
	30 µin
Contact Current Rating (Max)	.5 A

Termination Features

Termination Method to PCB	Surface Mount - Solder Ball

Mechanical Attachment

Connector Mounting Type Board Mount



Packaging Features

Tray Color	Black
Packaging Method	Tray/Box

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JAN 2025 (247) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

Compatible Parts





TE Part # 2376823-1 LGA7529 SOCKET COVER





Customers Also Bought











TE Part #2-2340321-1
ASSY STRADDLE MOUNT 168P 093
SLIVER 2.0

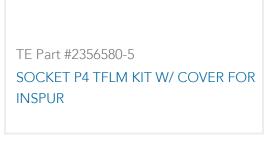


TE Part #2-2347090-1 SOCKET 4677 DG1.0 FOR ODM









Documents

Product Drawings
PACKAGE, SOCKET LGA 7529

English

CAD Files

3D PDF

3D

Customer View Model ENG_CVM_CVM_2375157-1_2.3d_stp.zip

LGA 7529, 7529 Position, Surface Mount - Solder Ball, .81389 x .9398 mm Grid, Board Mount, LGA Sockets



English

Customer View Model

ENG_CVM_CVM_2375157-1_2.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2375157-1_2.3d_igs.zip

English

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